

MA27P11

Silicon epitaxial planar type

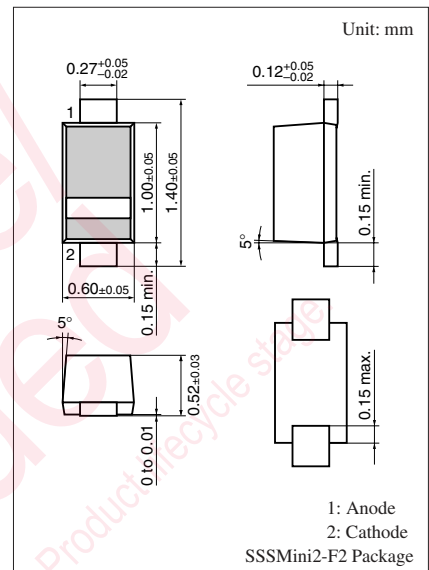
For high frequency switch

■ Features

- Low terminal capacitance
- Low forward dynamic resistance
- SSS-Mini type 2-pin package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Forward current	I_F	50	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

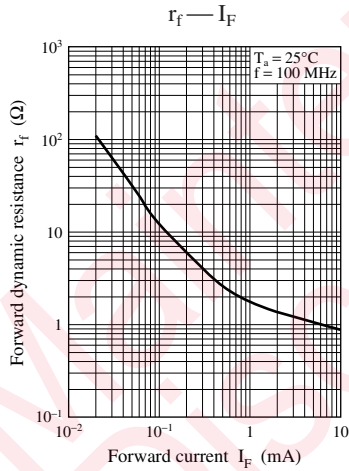
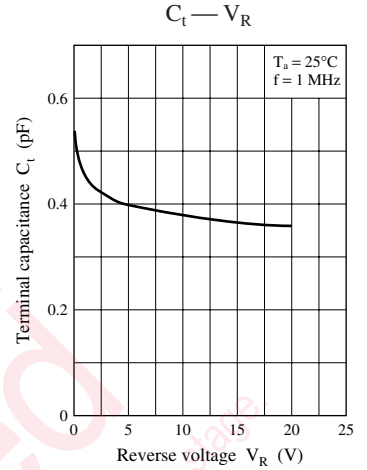
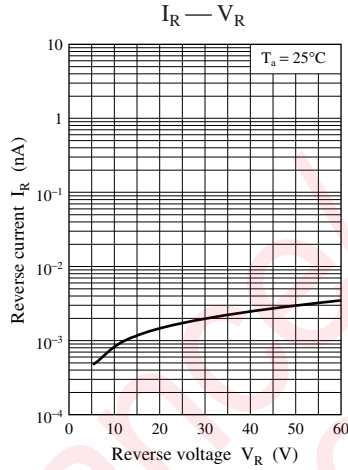
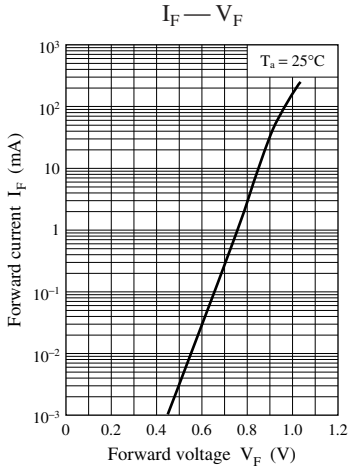


Marking Symbol: F

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$		0.76	0.85	V
	V_{F2}	$I_F = 10 \text{ mA}$		0.85	1.00	V
Reverse current	I_R	$V_R = 60 \text{ V}$		1.0	100	nA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		0.55	0.80	pF
Forward dynamic resistance	r_{f1}	$I_F = 1 \text{ mA}, f = 100 \text{ MHz}$		1.6	3.0	Ω
	r_{f2}	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$		0.9	1.5	Ω

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.



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 maintenance type
 planned discontinued type
 discontinued type
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